

74HC30-Q100; 74HCT30-Q100

8-input NAND gate

Rev. 1 — 30 January 2013

Product data sheet

1. General description

The 74HC30-Q100; 74HCT30-Q100 is an 8-input NAND gate. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from -40°C to $+85^{\circ}\text{C}$ and from -40°C to $+125^{\circ}\text{C}$
- Complies with JEDEC standard JESD7A
- Input levels:
 - ◆ For 74HC30-Q100: CMOS level
 - ◆ For 74HCT30-Q100: TTL level
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V ($C = 200 \text{ pF}$, $R = 0 \Omega$)
- Multiple package options

3. Ordering information

Table 1. Ordering information

Type number	Package				Version
	Temperature range	Name	Description		
74HC30D-Q100	-40°C to $+125^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm		SOT108-1
74HCT30D-Q100					
74HC30PW-Q100	-40°C to $+125^{\circ}\text{C}$	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm		SOT402-1
74HCT30PW-Q100					



4. Functional diagram

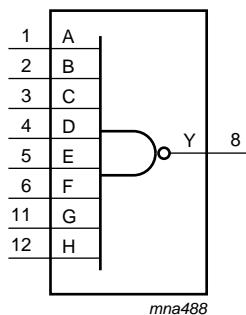


Fig 1. Logic symbol

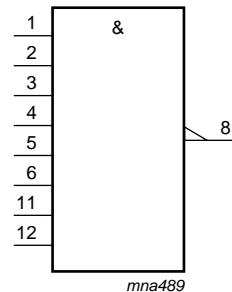


Fig 2. IEC logic symbol

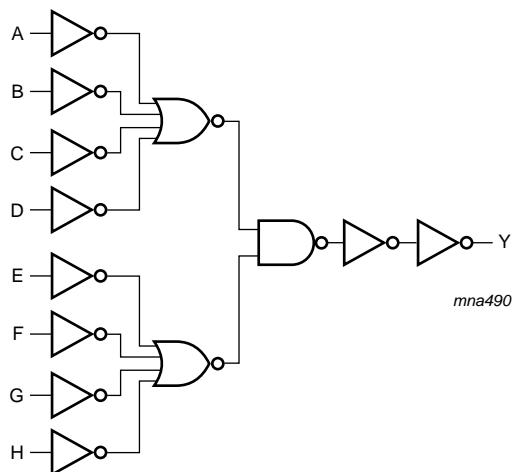


Fig 3. Logic diagram

5. Pinning information

5.1 Pinning

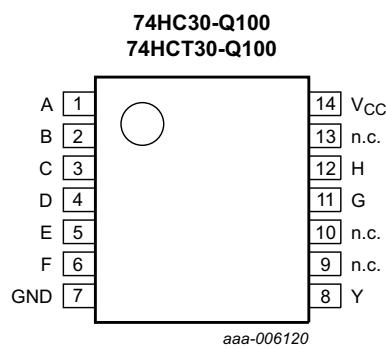


Fig 4. Pin configuration SO14 and TSSOP14

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
A	1	data input
B	2	data input
C	3	data input
D	4	data input
E	5	data input
F	6	data input
GND	7	ground (0 V)
Y	8	data output
n.c.	9	not connected
n.c.	10	not connected
G	11	data input
H	12	data input
n.c.	13	not connected
V _{CC}	14	supply voltage

6. Functional description

Table 3. Function table^[1]

Input								Output
A	B	C	D	E	F	G	H	Y
L	X	X	X	X	X	X	X	H
X	L	X	X	X	X	X	X	H
X	X	L	X	X	X	X	X	H
X	X	X	L	X	X	X	X	H
X	X	X	X	L	X	X	X	H
X	X	X	X	X	L	X	X	H
X	X	X	X	X	X	L	X	H
X	X	X	X	X	X	X	L	H
H	H	H	H	H	H	H	H	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7	V
I _{IK}	input clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V	[1] -	±20	mA
I _{OK}	output clamping current	V _O < -0.5 V or V _O > V _{CC} + 0.5 V	[1] -	±20	mA
I _O	output current	-0.5 V < V _O < V _{CC} + 0.5 V	-	±25	mA
I _{CC}	supply current		-	50	mA
I _{GND}	ground current		-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation		[2] -	500	mW
	SO14 and TSSOP14 packages				

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO14 package: P_{tot} derates linearly with 8 mW/K above 70 °C.
For TSSOP14 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC30-Q100			74HCT30-Q100			Unit
			Min	Typ	Max	Min	Typ	Max	
V _{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V _I	input voltage		0	-	V _{CC}	0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	-	+125	-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 2.0 V	-	-	625	-	-	-	ns/V
		V _{CC} = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V _{CC} = 6.0 V	-	-	83	-	-	-	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC30-Q100										
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = −20 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = −20 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = −20 μA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I _O = −4.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I _O = −5.2 mA; V _{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = 20 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1	-	±1	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	2.0	-	20	-	40	μA

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
C_I	input capacitance		-	3.5	-	-	-	-	-	pF
74HCT30-Q100										
V_{IH}	HIGH-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2.0	1.6	-	2.0	-	2.0	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	1.2	0.8	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 4.5 \text{ V}$	$I_O = -20 \mu\text{A}$	4.4	4.5	-	4.4	-	4.4	V
			$I_O = -4.0 \text{ mA}$	3.98	4.32	-	3.84	-	3.7	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 4.5 \text{ V}$	$I_O = 20 \mu\text{A}$	-	0	0.1	-	0.1	-	V
			$I_O = 4.0 \text{ mA}$	-	0.15	0.26	-	0.33	-	V
I_I	input leakage current	$V_I = V_{CC} \text{ or GND}; V_{CC} = 5.5 \text{ V}$	-	-	± 0.1	-	± 1	-	± 1	μA
I_{CC}	supply current	$V_I = V_{CC} \text{ or GND}; I_O = 0 \text{ A}; V_{CC} = 5.5 \text{ V}$	-	-	2.0	-	20	-	40	μA
ΔI_{CC}	additional supply current	per input pin; $V_I = V_{CC} - 2.4 \text{ V}; I_O = 0 \text{ A};$ other inputs at V_{CC} or GND; $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	60	216	-	275	-	294	μA
C_I	input capacitance		-	3.5	-	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics $GND = 0 \text{ V}; C_L = 50 \text{ pF}$; for test circuit see [Figure 6](#).

Symbol	Parameter	Conditions	25 °C			−40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	
74HC30-Q100								
t_{pd}	propagation delay	A, B, C, D, E, F, G, H to Y; see Figure 5	[1]					
		$V_{CC} = 2.0 \text{ V}$	-	41	130	165	195	ns
		$V_{CC} = 4.5 \text{ V}$	-	15	26	33	39	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$	-	12	-	-	-	ns
		$V_{CC} = 6.0 \text{ V}$	-	12	22	28	33	ns
t_t	transition time	see Figure 5	[2]					
		$V_{CC} = 2.0 \text{ V}$	-	19	75	95	110	ns
		$V_{CC} = 4.5 \text{ V}$	-	7	15	19	22	ns
		$V_{CC} = 6.0 \text{ V}$	-	6	13	16	19	ns

Table 7. Dynamic characteristics ...continued*GND = 0 V; $C_L = 50 \text{ pF}$; for test circuit see [Figure 6](#).*

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	
C_{PD}	power dissipation capacitance	per package; $V_I = \text{GND to } V_{CC}$	[3]	-	15	-	-	pF
74HCT30-Q100								
t_{pd}	propagation delay	A, B, C, D, E, F, G, H to Y; see Figure 5	[1]					
		$V_{CC} = 4.5 \text{ V}$		-	16	28	35	42
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$		-	12	-	-	ns
t_t	transition time	$V_{CC} = 4.5 \text{ V}$; see Figure 5	[2]	-	7	15	19	22
C_{PD}	power dissipation capacitance	per package; $V_I = \text{GND to } V_{CC} - 1.5 \text{ V}$	[3]	-	15	-	-	pF

[1] t_{pd} is the same as t_{PHL} and t_{PLH} .[2] t_t is the same as t_{THL} and t_{TLH} .[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

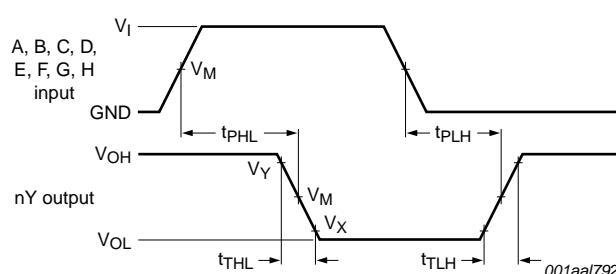
$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

 f_i = input frequency in MHz; f_o = output frequency in MHz; C_L = output load capacitance in pF; V_{CC} = supply voltage in V;

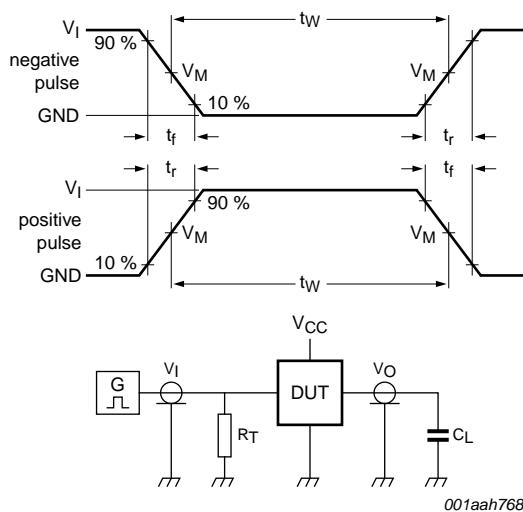
N = number of inputs switching;

 $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms

Measurement points are given in [Table 8](#). V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.**Fig 5. Input to output propagation delays****Table 8. Measurement points**

Type	Input	Output		
		V_M	V_M	V_X
74HC30-Q100	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT30-Q100	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$



Test data is given in [Table 9](#).

Definitions for test circuit:

R_T = termination resistance should be equal to the output impedance Z_0 of the pulse generator.

C_L = load capacitance including jig and probe capacitance.

Fig 6. Test circuit for measuring switching times

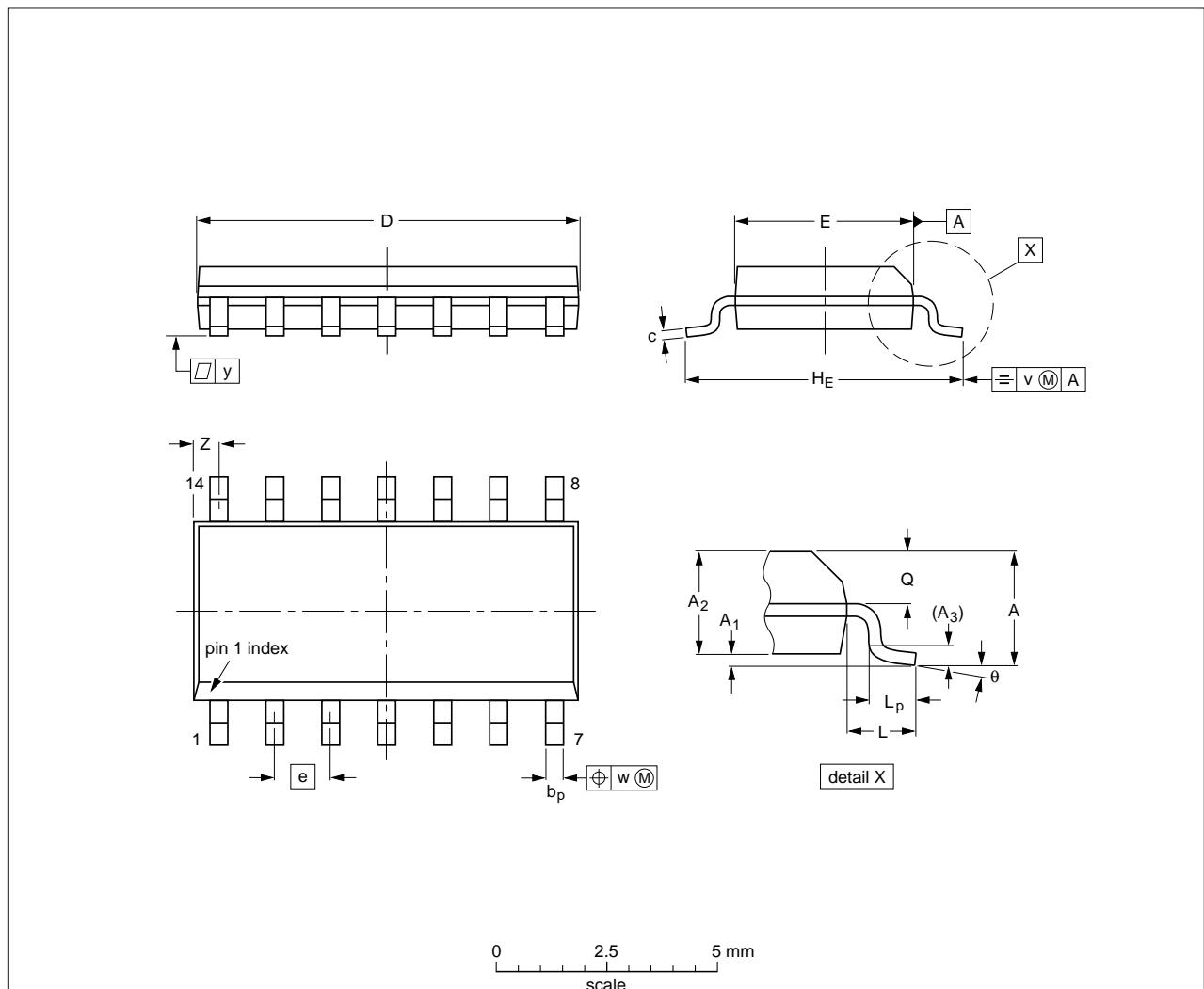
Table 9. Test data

Type	Input		Load	Test
	V_I	t_r, t_f		
74HC30-Q100	V_{CC}	6.0 ns	15 pF, 50 pF	t_{PLH}, t_{PHL}
74HCT30-Q100	3.0 V	6.0 ns	15 pF, 50 pF	t_{PLH}, t_{PHL}

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.75	0.25	1.45	0.25	0.49	0.25	8.75	4.0	1.27	6.2	1.05	1.0	0.7	0.25	0.25	0.1	0.7	8°
inches	0.069	0.010	0.057	0.01	0.019	0.0100	0.35	0.16	0.05	0.244	0.041	0.039	0.028	0.01	0.01	0.004	0.028	0°

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT108-1	076E06	MS-012				99-12-27 03-02-19

Fig 7. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

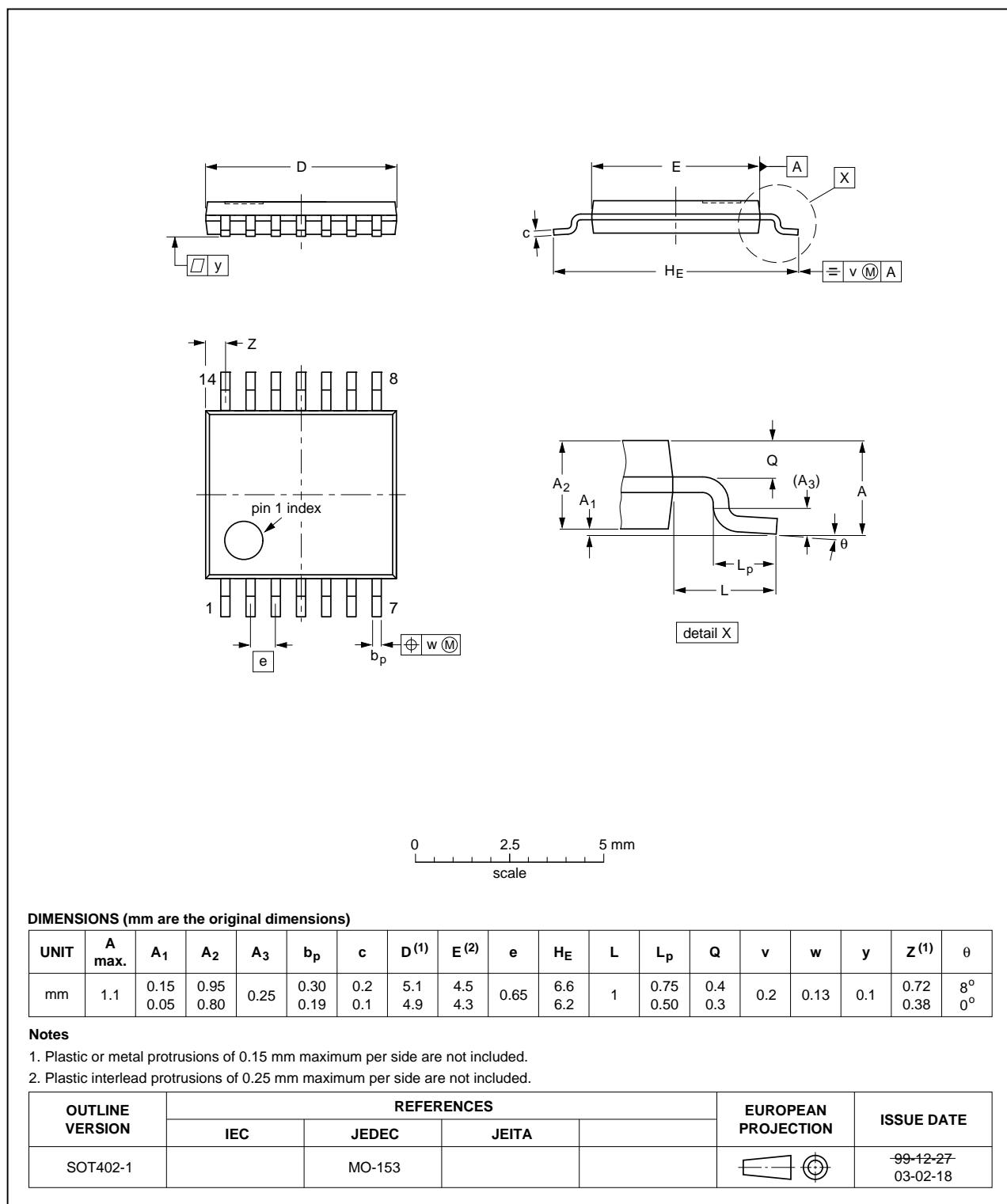


Fig 8. Package outline SOT402-1 (TSSOP14)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model
MIL	Military
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT30_Q100 v.1	20130130	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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